

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Alfred W. Mak, et al.

Serial No.: 09/885,609

Filed:

June 20, 2001

Confirmation No.: 5337

For:

SYSTEM AND METHOD TO

FORM A COMPOSITE FILM

STACK UTILIZING

SEQUENTIAL DEPOSITION

TECHNIQUES

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Group Art Unit: 2818

Examiner:

Berry, Renee R.

MAIL STOP RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service on February 26, 2004, in an envelope marked as "Express Mail United States Postal Service", Mailing Label No. EV 335470440 US, addressed to: Commissioner for Patents, Mail Stop RCE, P.O. Box 1450

Alexandria, VA 22313-1450.

2/26/2004

Signature

PRELIMINARY AMENDMENT

Prior to examination, please amend the above-identified application as follows:

In the Claims:

Please amend claim 7 as follows:

1. (Previously presented) A method for forming a stacked barrier layer on a substrate disposed in a processing chamber, comprising:

serially exposing said substrate to first and second reactive gases to form an adhesion layer; and